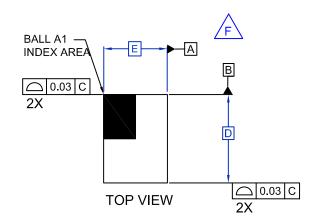
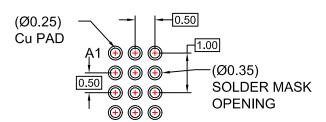
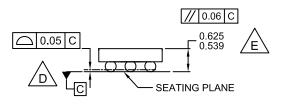
## WLCSP12 2.2x1.43x0.582 CASE 567PX ISSUE O

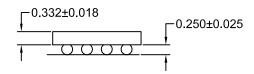
**DATE 31 OCT 2016** 



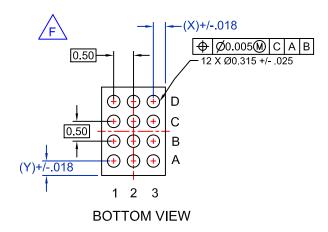


RECOMMENDED LAND PATTERN (NSMD)





SIDE VIEWS



## NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- PACKAGE TYPICAL HEIGHT IS 582 MICRONS ± 38 MICRONS (539-625 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP12 2.2x1.43x0.582		PAGE 1 OF 1

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